



VMDSEMI

**VUPA003R085NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
30V	8.5mΩ@10V	45A
	14mΩ@4.5V	

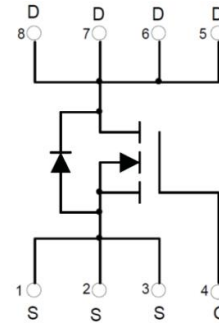
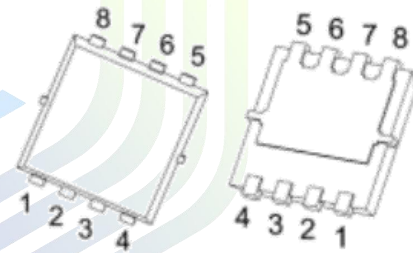


Figure 1 Symbol of VUPA003R085NA

## Features

- Low  $R_{DS(ON)}$
- Trench Technology Power MOSFET
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

## Package Type



**PDFN3.3×3.3-8L**

## Application

- Power Switch
- Battery protection applications

Figure 2 Package Type of VUPA003R085NA

## Ordering Information

Product Name	Package
VUPA003R085NA	PDFN3.3X3.3-8L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup> $T_C = 25\text{ °C}$	$I_D$	45	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	180	A
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	19	mJ
Avalanche Current <sup>Note3</sup>	$I_{AS}$	90	A
Total Power Dissipation <sup>Note5</sup> $T_C = 25\text{ °C}$	$P_D$	25	W
Total Power Dissipation <sup>Note6</sup> $T_A = 25\text{ °C}$	$P_D$	1.6	
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

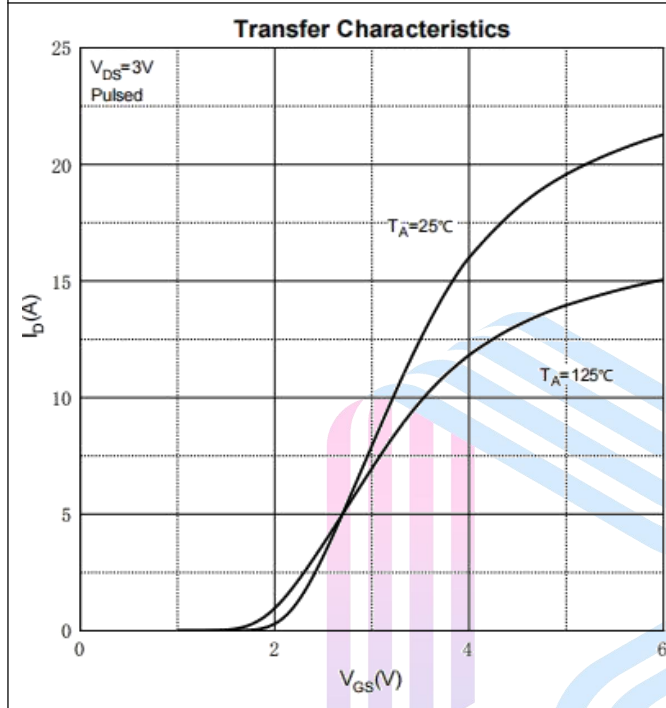
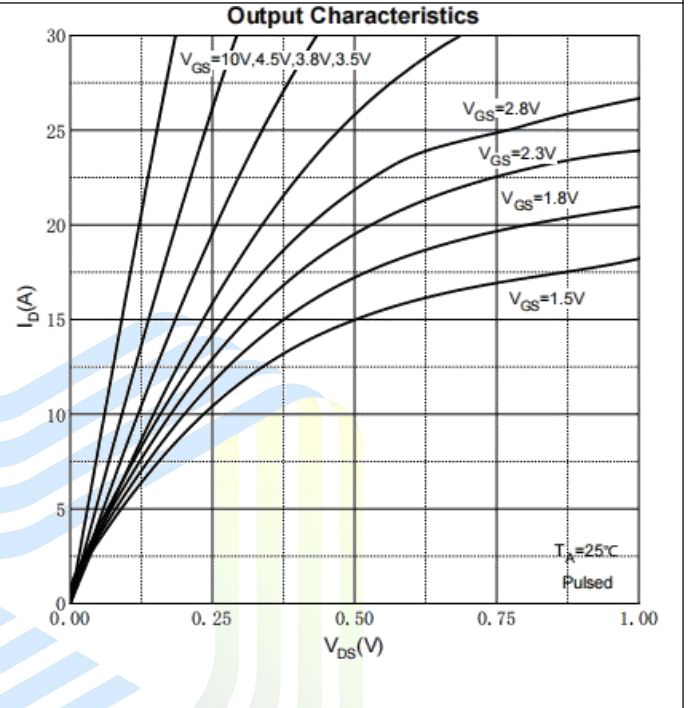
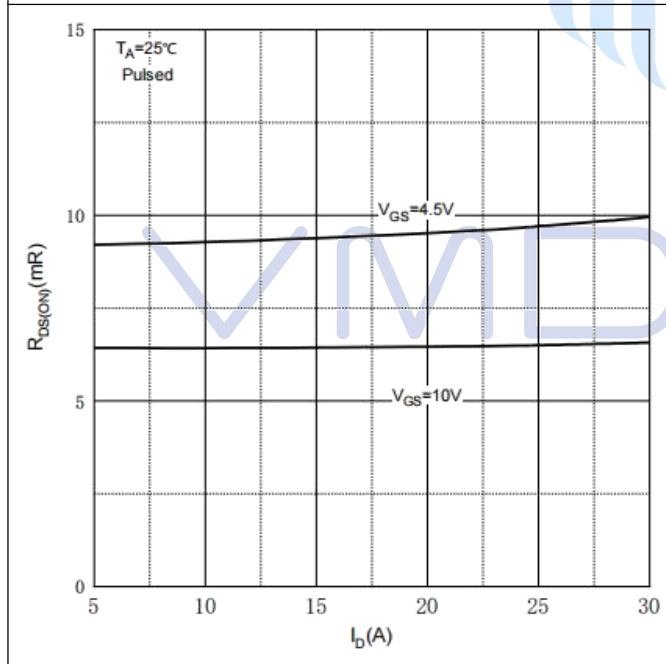
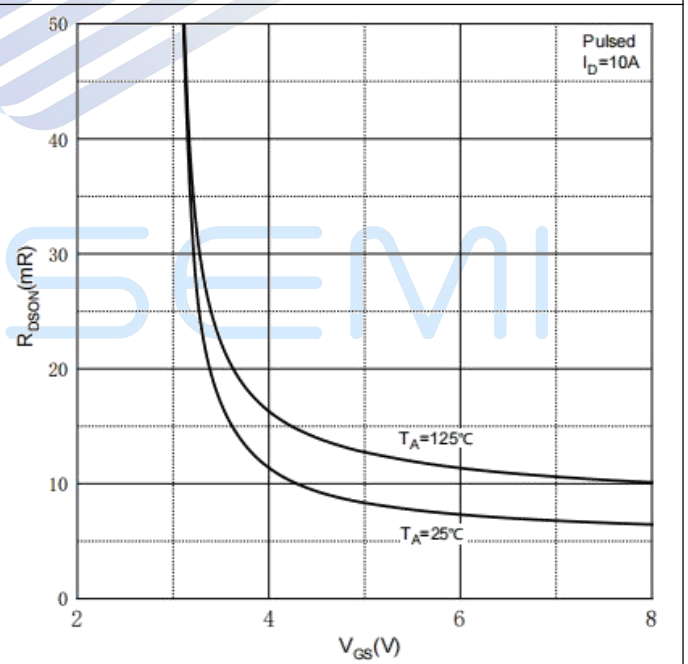
Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		75		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		5		°C/W

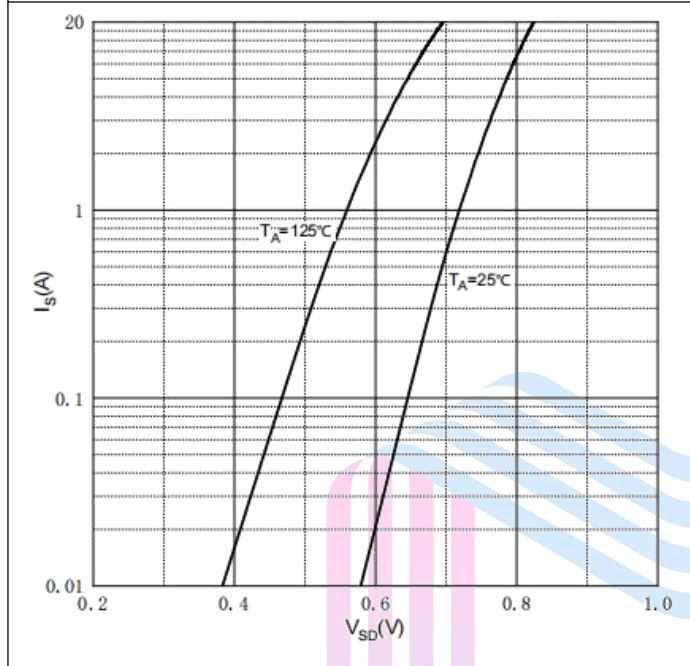
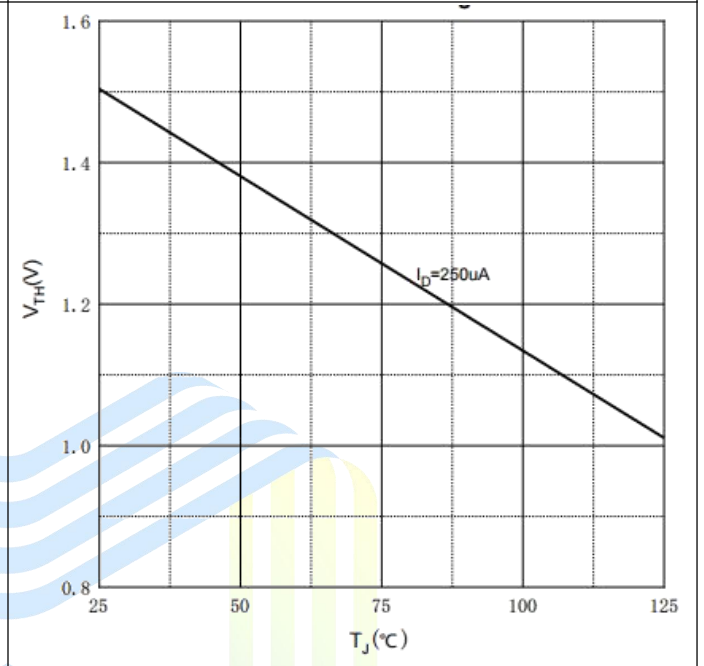
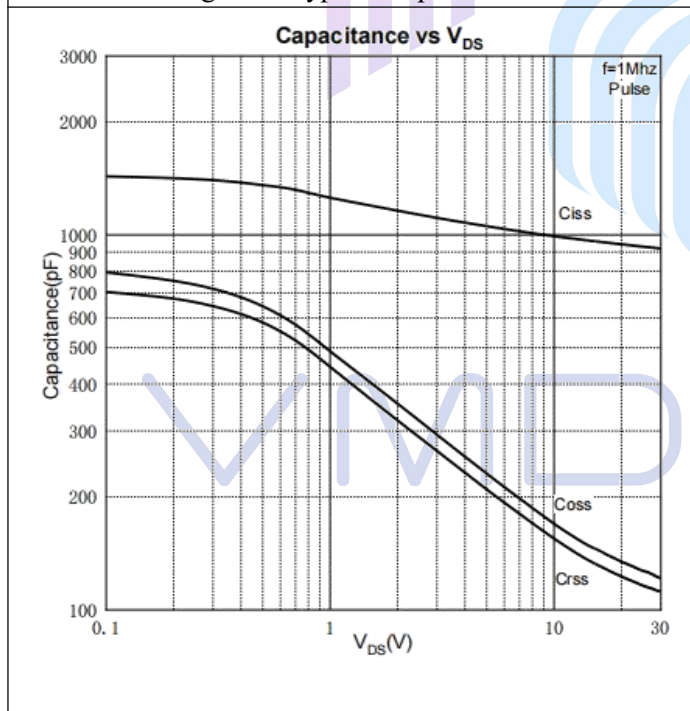
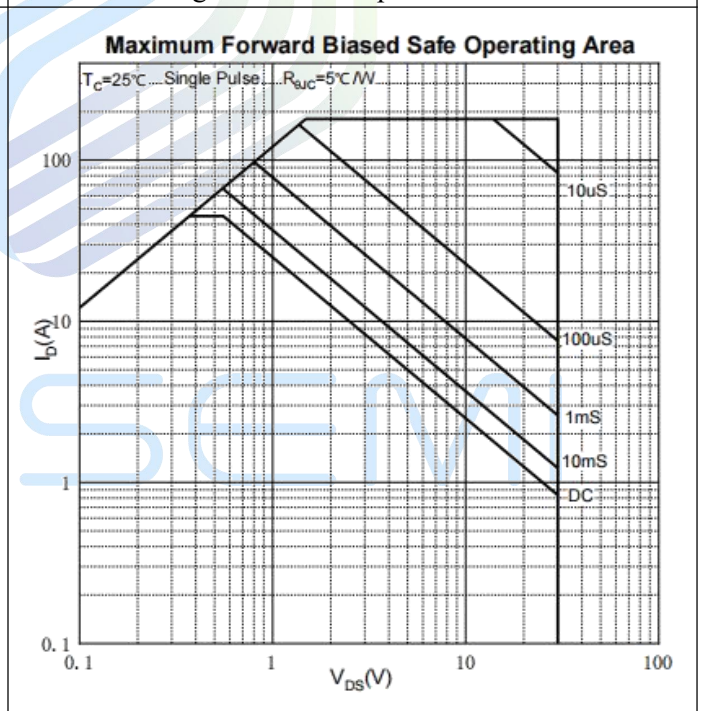
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

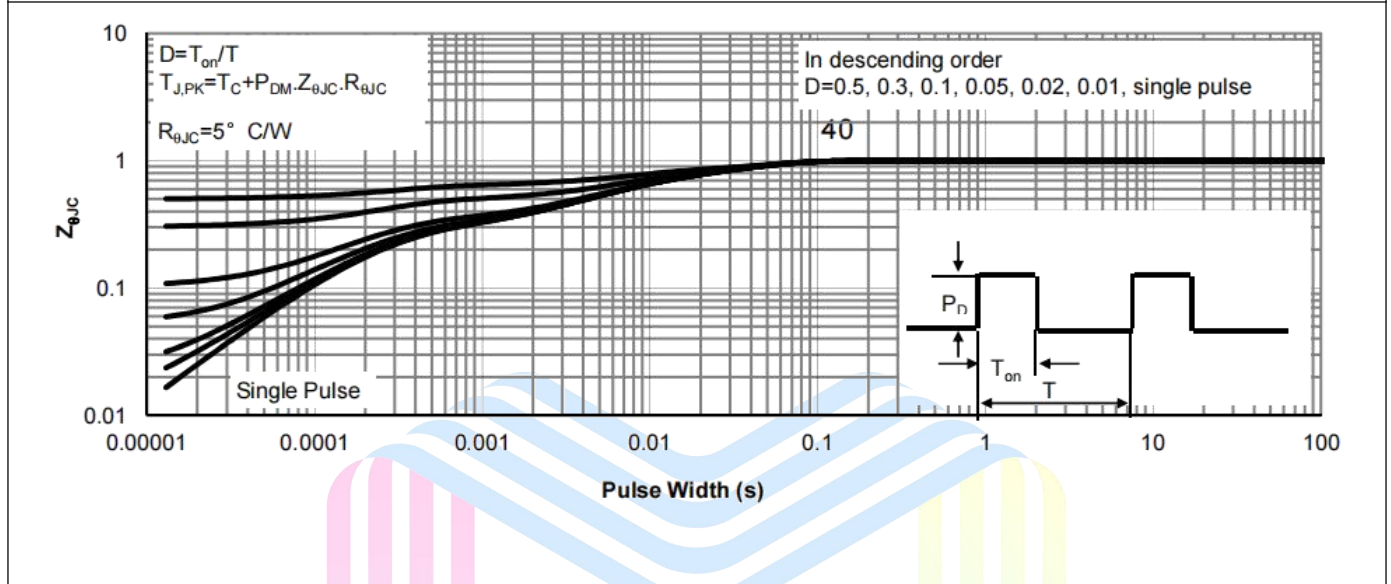
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=24V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		6.5	8.5	mΩ
		$V_{GS}=4.5V, I_D=20A$		9.5	14	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=15V$		990.2		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		143.7		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		128.2		pF
Total Gate Charge	$Q_g$	$V_{DS}=15V$		22.2		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=4.5V$		3.0		
Gate-Drain Charge	$Q_{gd}$	$I_D=20A$		4.3		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.95		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$		6.5		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		2		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.75\Omega$		17		
Turn-off Fall Time	$t_f$	$R_{GEN}=3\Omega$		3.5		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

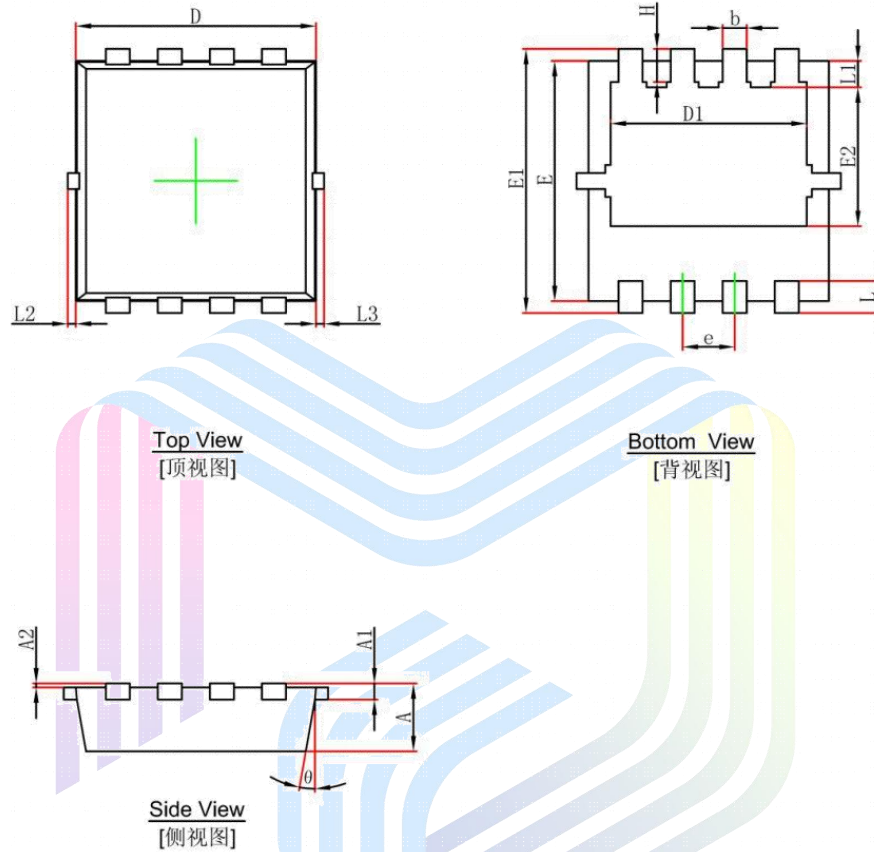
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 15V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

**Typical Performance Characteristics**
**Figure 3: Transfer Characteristics**

**Figure 4: Output Characteristics**

**Figure 5: On-Resistance vs. Drain Current**

**Figure 6: On-Resistance vs. Gate Voltage**


**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**


**Figure 11: Normalized Maximum Transient Thermal Impedance**



# VMDSEMI

**Mechanical Dimensions:**
**PDFN3.3×3.3-8L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°



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